

Title (en)

METHOD FOR PRODUCTION OF ELECTRONIC AND OPTOELECTRONIC CIRCUITS

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ELEKTRONISCHEN UND OPTOELEKTRONISCHEN SCHALTUNGEN

Title (fr)

PROCEDE DE FABRICATION DE CIRCUITS ELECTRONIQUES ET OPTOELECTRONIQUES

Publication

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Application

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Abstract (en)

[origin: WO2005104314A2] The invention relates to an assembly comprising an electronic component (108), said electronic component being connected by microbeads (107) to at least one heat sink (106, 109), said beads being connected to electrically-conducting lines on said electronic component and to electrically-conducting lines on at least one heat sink, said beads transporting electrical signals between the electronic component and each heat sink with said electrically-conducting lines and, by thermal conduction, heat from the electronic component to each heat sink.

IPC 8 full level

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CPC (source: EP US)

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